

Electronic Patent Application Fee Transmittal

Application Number:	10695187			
Filing Date:	28-Oct-2003			
Title of Invention:	Vertical removal of excess solder from a circuit substrate			
First Named Inventor:	William C. Weigler			
Filer:	Paul M. Hletko/David Hawkins			
Attorney Docket Number:	IS01207AP			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	500	500
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500